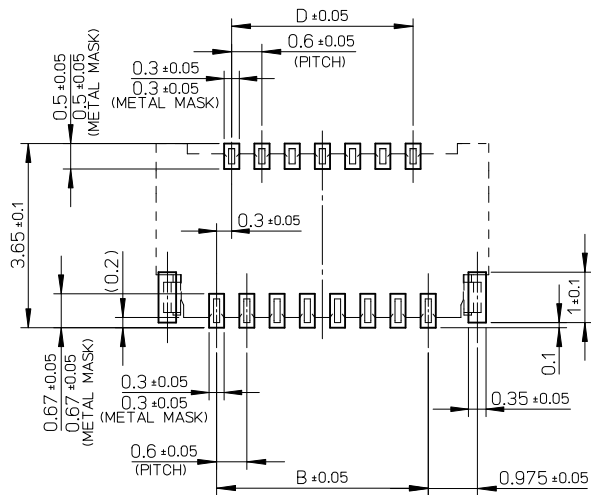


注記 NOTES:
 1.材質 MATERIAL
 ハウジング: LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER, WHITE (NATURAL)
 GLASS FILLED, UL94V-0
 アクチュエータ: ポリアミド樹脂
 黒色、ガラス充填、UL94V-HB
 ACTUATOR: POLYAMIDE
 BLACK GLASS FILLED, UL94V-HB
 ターミナル: 銅合金 (t=0.12)
 TERMINAL: COPPER ALLOY (t=0.12)
 金具: 燐青銅 (t=0.15)
 NAIL: PHOSPHOR BRONZE (t=0.15)
 2.めっき仕様 PLATING
 ターミナル TERMINAL
 接点部: 金めっき 0.1μm以上
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
 半田付け部: 金めっき
 SOLDER TAIL AREA: GOLD
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 金具 NAIL
 錫めっき 1.0μm以上
 TIN PLATING 1.0 MICROMETER MINIMUM
 下地めっき: ニッケル 1.0μm以上
 UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
 3.平坦度は、0.1ミリ以下とする。
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.
 4.製品の取り扱いについては、コネクタ取り扱い説明書 (AS-502598-001) を参照願います。
 PLEASE REFER TO INSTRUCTION MANUAL (AS-502598-001) FOR 0.3 FPC CONNECTOR BACK FLIP.
 5.ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

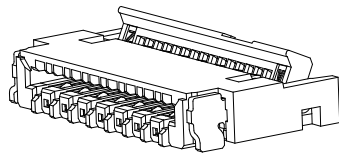
0.125	14.4	16.95	15	17.4	502598-5191	51
0.112	12.6	15.15	13.2	15.6	502598-4591	45
0.098	10.8	13.35	11.4	13.8	502598-3991	39
0.085	9	11.55	9.6	12	502598-3391	33
0.077	7.8	10.35	8.4	10.8	502598-2991	29
0.072	7.2	9.75	7.8	10.2	502598-2791	27
0.068	6.6	9.15	7.2	9.6	502598-2591	25
0.063	6	8.55	6.6	9	502598-2391	23
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES NO. 502598-***11

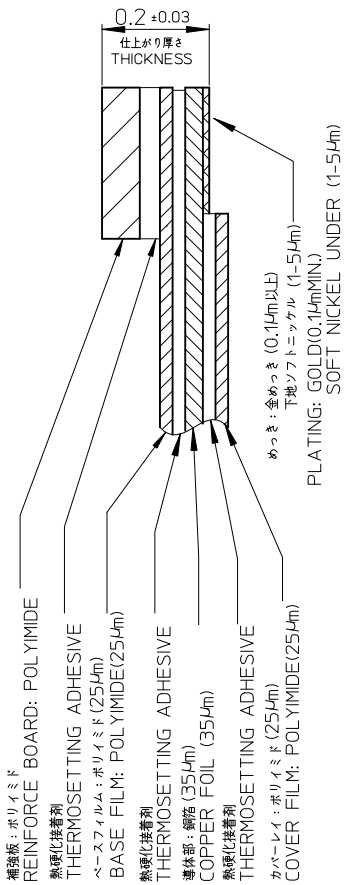
REVISED EC NO: J2012-0121 DRWN: YUHASEGAWA 2011/07/25 CHKD: TAKAHASHI 2011/07/25 APPR: KMORIKAWA 2011/07/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION 0.3 FPC CONN. BACK FLIP HOUSING ASSY MOLEX INCORPORATED SD-502598-001 SHEET NO. 1 OF 2
	10 UNDER ±0.2		MM ONLY	20:1	METRIC	
	10 OVER 30 UNDER ±0.25		DRAWN BY	DATE	TITLE	
	30 OVER ±0.3		HONO	2009/07/21	0.3 FPC CONN. BACK FLIP HOUSING ASSY	
DESCRIPTION REV C	ANGULAR ±1 °		CHECKED BY	DATE	MOLEX DOCUMENT NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		HSHIMOYAMA	2009/07/21		
			APPROVED BY	DATE		
			KMORIKAWA	2009/07/21	SEE TABLE	SD-502598-001
			MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



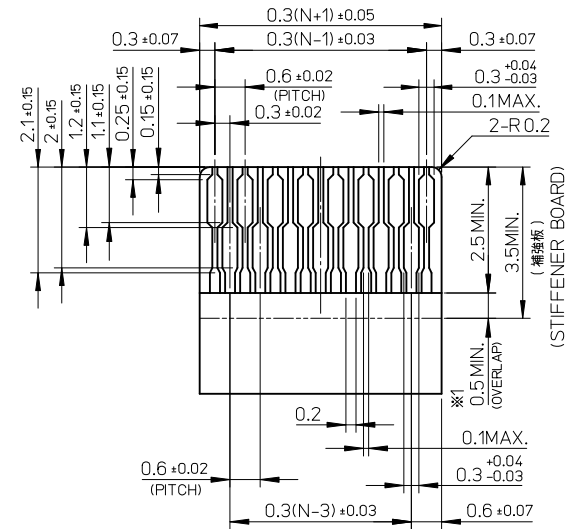
推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
推奨メタルマスク厚: t=0.1mm
RECOMMENDED METAL MASK THICKNESS: t=0.1mm



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

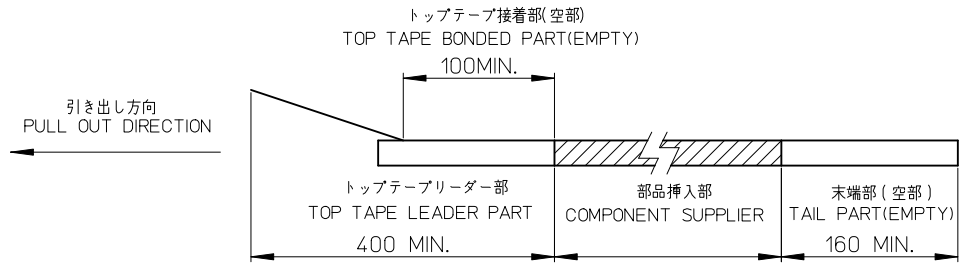
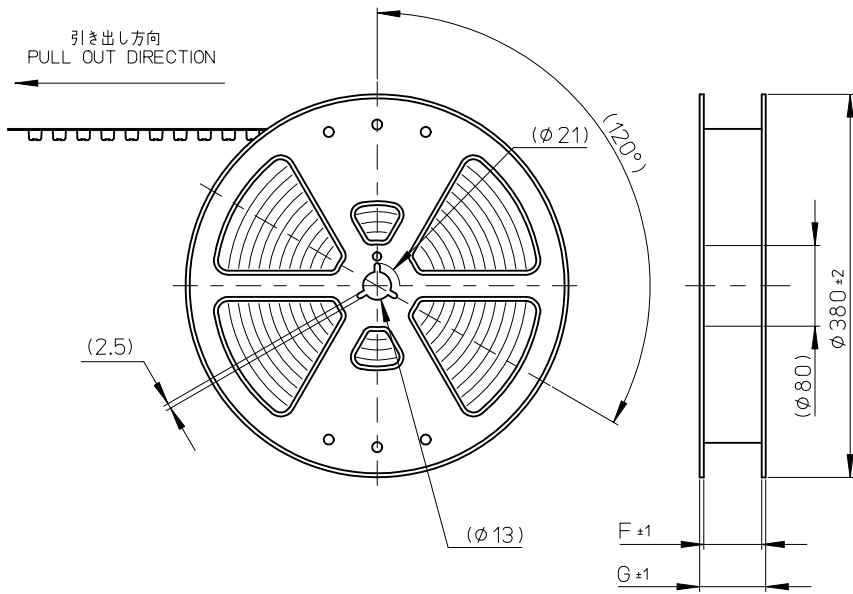
※1 補強板の長さが図面通りに確保できない場合は、カバーレイと
補強板のオーバーラップ寸法を0.5mm以上としてください。
WHEN STIFFENER BOARD DIMENSION CAN NOT SECURE
AS DRAWING, PLEASE GIVE THE OVERLAP SIZE OF
COVER FILM AND STIFFNER BOARD AS 0.5mm MINIMUM.

N : 極数
N:CIRCUITS

REVISED	EC NO: J2012-0121	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	DRWN:YUHASEGAMA 2011/07/25		CHKD:KATAHASHI 2011/07/25	APPR:KMORIKAWA 2011/07/28	10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	MM ONLY	++	METRIC	⊙ □
C	REV	REV	30 OVER ±0.3	ANGULAR ±1 °	DRAWN BY	DATE	TITLE			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	HONO	2009/07/21	0.3 FPC CONN. BACK FLIP HOUSING ASSY			
MATERIAL NO.			APPROVED BY		DATE	MOLEX		MOLEX INCORPORATED		
SD-502598-001			KMORIKAWA		2009/07/21	DOCUMENT NO.		SD-502598-001		
SIZE			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		A3		SHEET NO.		2 OF 2	

注記)
NOTES

1. 製品番号502598-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 502598-**11 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

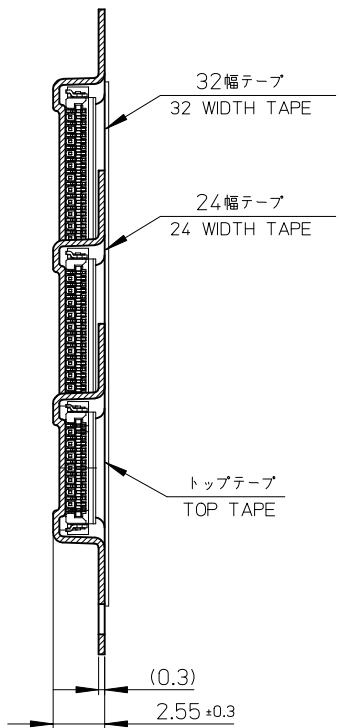
5. 材料

MATERIAL

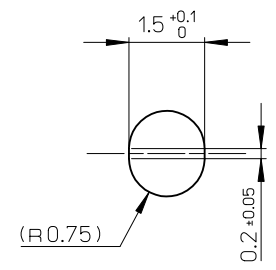
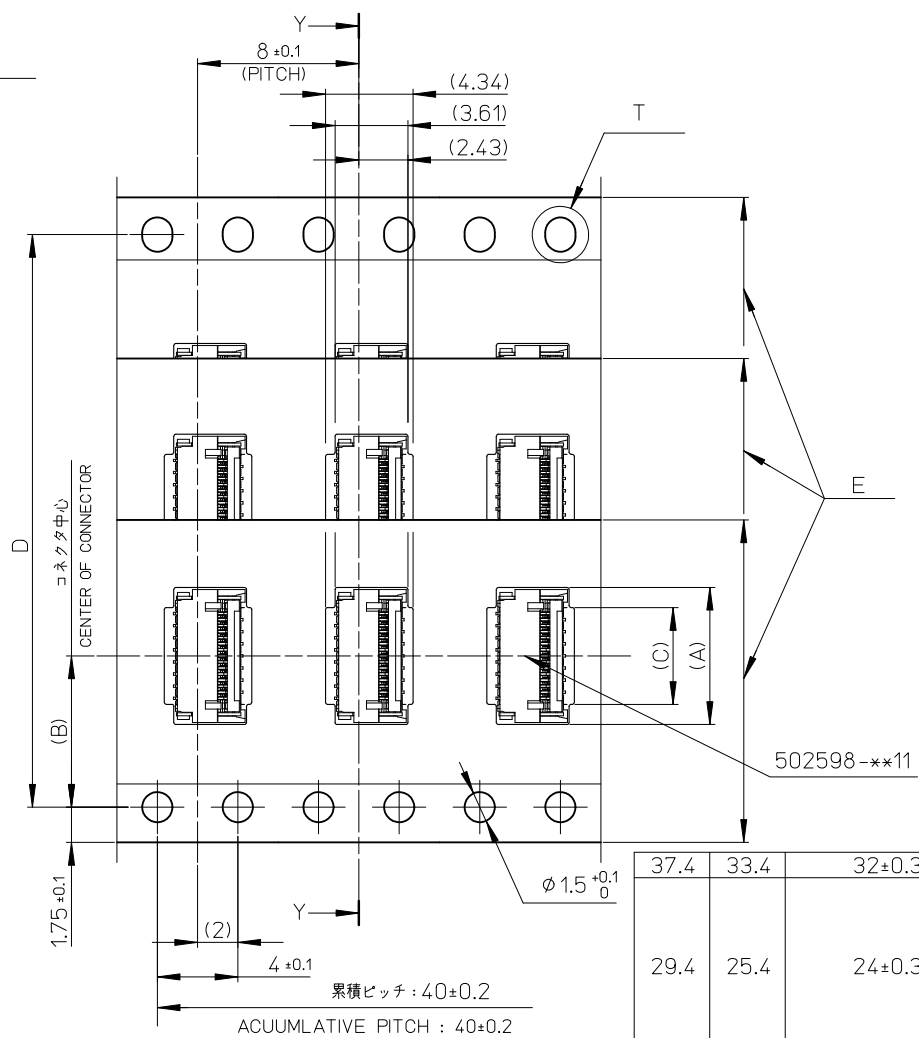
- キャリアテープ: ポリスチレン (PS)
 - CARRIER TAPE: POLYSTYRENE (PS)
 - トップテープ: ポリエチレンテレフタレート (PET)、他
 - TOP TAPE : POLYETHYLENE TELEPHTHALATE (PET), OTHERS
 - リール: ポリスチレン (PS)
 - REEL: POLYSTYRENE (PS)
6. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2011-0028 DRWN: HONO01 2010/07/06 CH'KD: HSHIMOYAMA 2009/07/21 APPR: KMORIKAWA 2010/07/08	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)				
		10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21	DOCUMENT NO. SD-502598-002				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

引き出し方向
PULL OUT DIRECTION



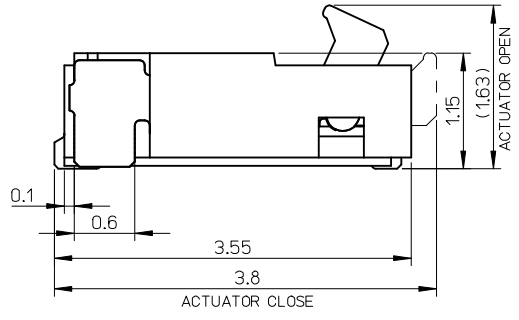
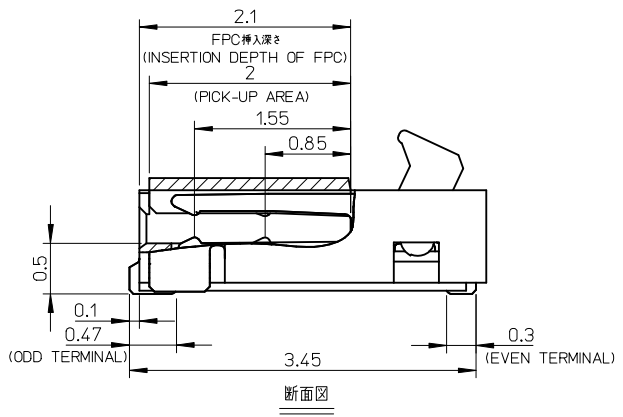
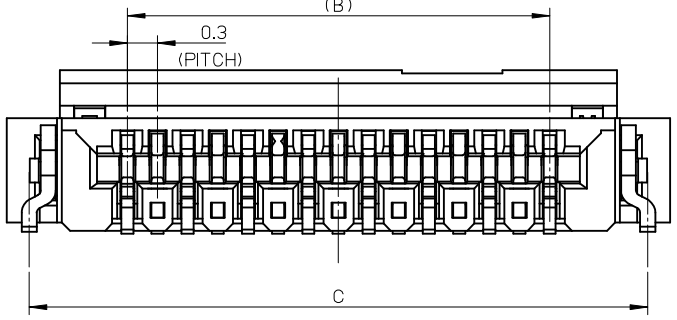
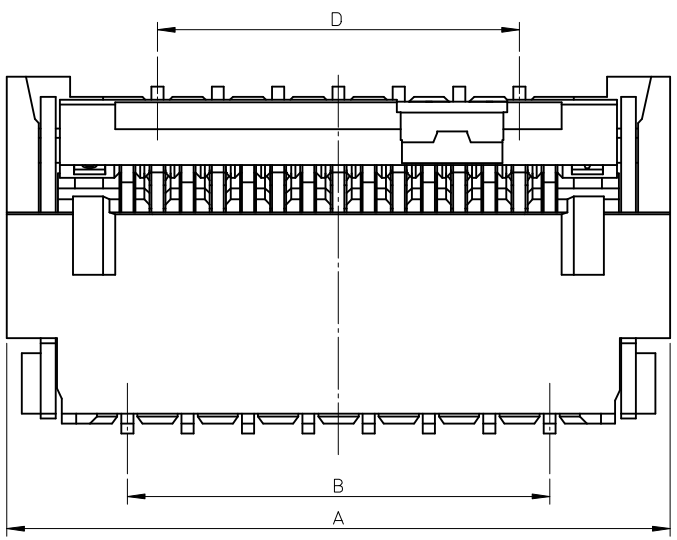
断面 Y-Y
SECTION Y-Y



T部詳細
DETAIL T

37.4	33.4	32 ±0.3	28.4	15.7	14.2	17.6	502598-5191	51
29.4	25.4	24 ±0.3	--	13.9	11.5	15.8	502598-4591	45
				12.1		14	502598-3991	39
				10.3		12.2	502598-3391	33
				9.1		11	502598-2991	29
				8.5		10.4	502598-2791	27
				7.9		9.8	502598-2591	25
				7.3		9.2	502598-2391	23
G	F	E キャリアテープ幅 EMBOSSD TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2011-0028 DRWN: HONO01 2010/07/06 CHKD: HSHIMOYAMA 2009/07/21 APPR: KMORIKAWA 2010/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY HONO	DATE 2009/07/21	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (502598-**11 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2009/07/21	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2009/07/21	DOCUMENT NO. SD-502598-002		SHEET NO. 2 OF 2	
	ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE				
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

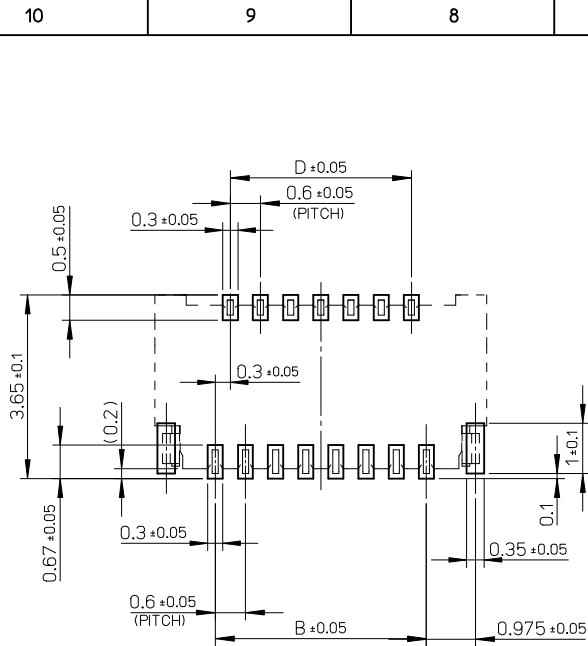


注記 NOTES:
 1.材質 MATERIAL
 ハウジング:LCP(液晶ポリマー)、白色、ガラス充填、UL94V-0
 HOUSING:LIQUID CRYSTAL POLYMER,WHITE(NATURAL)
 GLASS FILLED,UL94V-0
 アクチュエータ:ポリアミド樹脂
 黒色、ガラス充填、UL94HB
 ACTUATOR: POLYAMIDE
 BLACK GLASS FILLED,UL94HB
 ターミナル:焼青銅 (t=0.12)
 TERMINAL:PHOSPHOR BRONZE(t=0.12)
 金具:焼青銅(t=0.15)
 NAIL:PHOSPHOR BRONZE(t=0.15)
 2.めっき仕様 PLATING
 ターミナル TERMINAL
 接点部:金めっき 0.1μm以上
 CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM
 半田付け部:金めっき
 SOLDER TAIL AREA: GOLD
 下地めっき:ニッケル 1.0μm以上
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
 金具 NAIL
 錫めっき 1.0μm以上
 TIN PLATING 1.0 MICROMETER MINIMUM
 下地めっき:ニッケル 1.0μm以上
 UNDER PLATING:NICKEL 1.0 MICROMETER MINIMUM
 3.平坦度は、0.1ミリ以下とする。
 TAILS COPLANARITY TO BE 0.1 MAXIMUM.
 4.ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT
 5.本製品は502598-**91の端子材料変更品である。
 THIS PRODUCT IS CHANGE OF TERMINAL MATERIAL FOR 502598-**91.

0.125	14.4	16.95	15	17.4	502598-5193	51
0.112	12.6	15.15	13.2	15.6	502598-4593	45
0.105	11.4	13.95	12.0	14.4	502598-4193	41
0.098	10.8	13.35	11.4	13.8	502598-3993	39
0.085	9	11.55	9.6	12	502598-3393	33
0.077	7.8	10.35	8.4	10.8	502598-2993	29
0.072	7.2	9.75	7.8	10.2	502598-2793	27
0.068	6.6	9.15	7.2	9.6	502598-2593	25
0.063	6	8.55	6.6	9	502598-2393	23
0.048	4.2	6.75	4.8	7.2	502598-1793	17
0.043	3.6	6.15	4.2	6.6	502598-1593	15
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

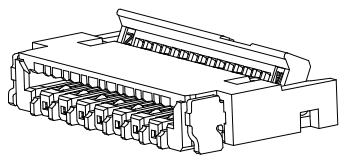
CONNECTOR SERIES NO. 502598-**21

REVISED IEC NO: J2014-0146 DRW:KINAGUMO 2013/07/25 CHKD:KATAHASHI 2013/08/30 APPR:YNOGAWA 2013/08/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION 0.3 FPC CONN. BACK FLIP HOUSING ASSY molex DOCUMENT NO. SD-502598-003 SHEET NO. 1 OF 2
	10 UNDER ±0.2		MM ONLY	---	METRIC	
	10 OVER 30 UNDER ±0.25		DRAWN BY DATE	TITLE		
	30 OVER ±0.3		KMIYAHARA 2012/07/18	0.3 FPC CONN. BACK FLIP HOUSING ASSY		
REV B	ANGULAR ±1 °		CHECKED BY DATE	MATERIAL NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		KTAKAHASHI 2012/07/18	SEE TABLE		
			APPROVED BY DATE	MATERIAL NO.		
		KMORIKAWA 2012/08/01	SEE TABLE			

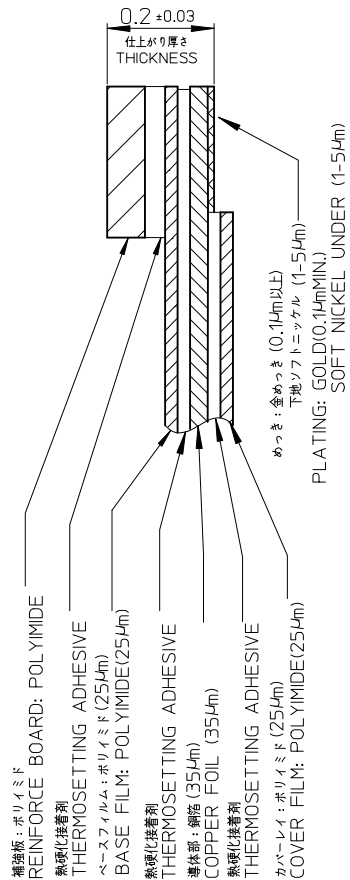


推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT

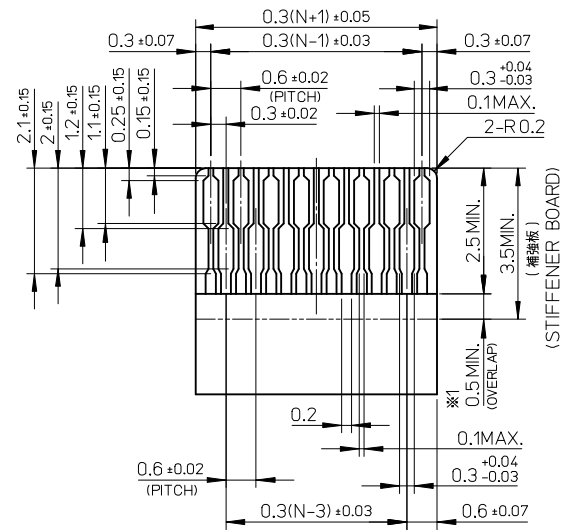
マスク厚: 100 μm
マスク開口率: 100%
SCREEN THICKNESS: 100 μm
SCREEN OPEN RATIO: 100%



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON
ADHEREND BECAUSE THERE IS A POSSIBILITY THAT
THE EXTRA ADHESIVE CAUSES THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2014-0146 DRWN: KIKAGURO 2013/07/25 CHKD: KAKAHASHI 2013/08/30 APPR: YNOGAWA 2013/08/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY KMIYAHARA	DATE 2012/07/18	TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY				
		10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/07/18	DOCUMENT NO. SD-502598-003				
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2012/08/01					
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				